

Docket No.  
IRV1.PAU.53

# Declaration and Power of Attorney For Patent Application

## English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

**STACKABLE LAYERS CONTAINING ENCAPSULATED INTEGRATED CIRCUIT CHIPS WITH ONE OR MORE OVERLYING INTERCONNECT LAYERS AND A METHOD OF MAKING THE SAME**

the specification of which

(check one)

☐ is attached hereto.

☒ was filed on 08/24/01 as United States Application No. or PCT International Application Number 09/938686 and was amended on \_\_\_\_\_

(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

Priority Not Claimed

(Number)

(Country)

(Day/Month/Year Filed)

☐

(Number)

(Country)

(Day/Month/Year Filed)

☐

(Number)

(Country)

(Day/Month/Year Filed)

☐

I hereby claim the benefit under 35 U.S.C. Section 119(e) of any United States provisional application(s) listed below:

_____	_____
(Application Serial No.)	(Filing Date)
_____	_____
(Application Serial No.)	(Filing Date)
_____	_____
(Application Serial No.)	(Filing Date)

I hereby claim the benefit under 35 U. S. C. Section 120 of any United States application(s), or Section 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C. F. R., Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

_____	_____	_____
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
_____	_____	_____
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
_____	_____	_____
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

**POWER OF ATTORNEY:** As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. *(list name and registration number)*

**Daniel L. Dawes, Reg. No. 27,123**

**Richard L. Myers, Reg. No. 26,490**

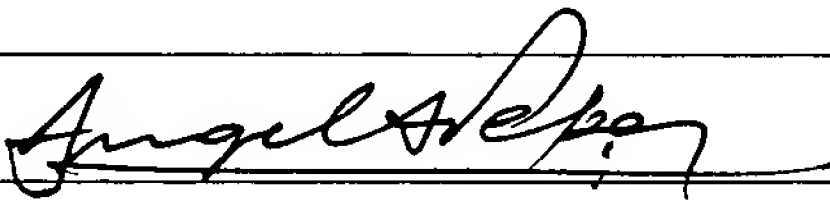
**Joseph C. Andras, Reg. No. 33,469**

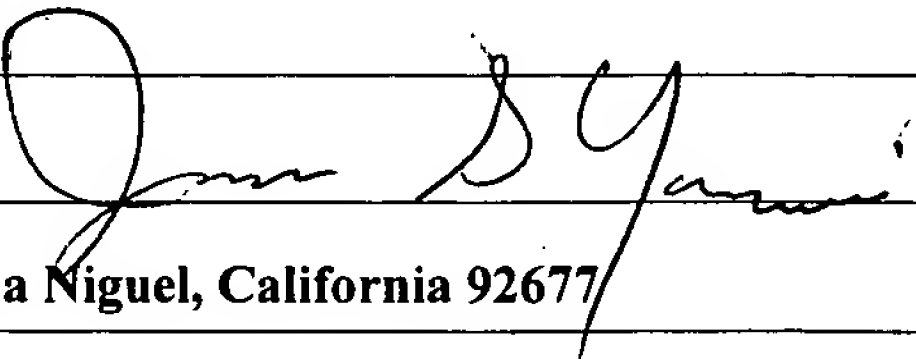
**David L. Henty, Reg. No. 31,323**

**Vic Y. Lin, Reg. No. 43,754**

**Send Correspondence to:** **Daniel L. Dawes**  
**MYERS, DAWES & ANDRAS LLP**  
**19900 MacArthur Boulevard, Suite 1150**  
**Irvine, California 92612**

**Direct Telephone Calls to:** *(name and telephone number)*  
**Daniel L. Dawes 949-223-9600**

Full name of sole or first inventor <b>Angel Antonio Pepe</b>	
Sole or first inventor's signature 	Date <b>8-28-01</b>
Residence <b>13 Banyan Tree Lane, Irvine, California 92612</b>	
Citizenship <b>US</b>	
Post Office Address	

Full name of second inventor, if any <b>James Satsuo Yamaguchi</b>	
Second inventor's signature 	Date <b>8-28-01</b>
Residence <b>29462 Castle Road, Laguna Niguel, California 92677</b>	
Citizenship <b>US</b>	
Post Office Address	

**ASSIGNMENT**

For good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S),

1. Angel A. Pepe 2. James S. Yamaguchi

hereby sells, assigns and transfers to Irvine Sensors Corporation, a Delaware corporation, having its statewide administrative offices located at 3001 Redhill Avenue, Suite 4-109, Costa Mesa, California 92626-4573 and the successors, assigns and legal representatives of the ASSIGNEE all of its right, title and interest for the United States and its territorial possessions and in all foreign countries in and to, any and all improvements which are disclosed in the invention entitled:

**STACKABLE LAYERS CONTAINING ENCAPSULATED INTEGRATED CIRCUIT CHIPS WITH ONE OR MORE OVERLYING INTERCONNECT LAYERS AND A METHOD OF MAKING THE SAME**

and which is found in

- (a) \_\_\_\_\_ U.S. provisional application filed herewith and listing the above named persons as inventors
- (b) \_\_\_\_\_ U.S. patent application filed herewith and listing the above named persons as inventors
- (c)   X   U.S. application serial no. 09/938686 filed on 8/24/01
- (d) \_\_\_\_\_ U.S. Patent No.: \_\_\_\_\_, issued \_\_\_\_\_

and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, continuation-in-part, extension, conversion to 35 USC 111(a) or substitute thereof, and any reissue, reexamination or extension of said Letters Patent and all under all International Conventions for the Protection of Industrial Property;

ASSIGNOR(S) hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR(S) further covenants that the ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation, or proceeding relating thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue or enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof. An attorney of record is authorized and requested by the execution of this assignment to insert into this assignment the filing date and serial number of said application when officially known.


AND the ASSIGNOR(S) requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States and any reissue or extension thereof to the ASSIGNEE, Irvine Sensors Corporation.

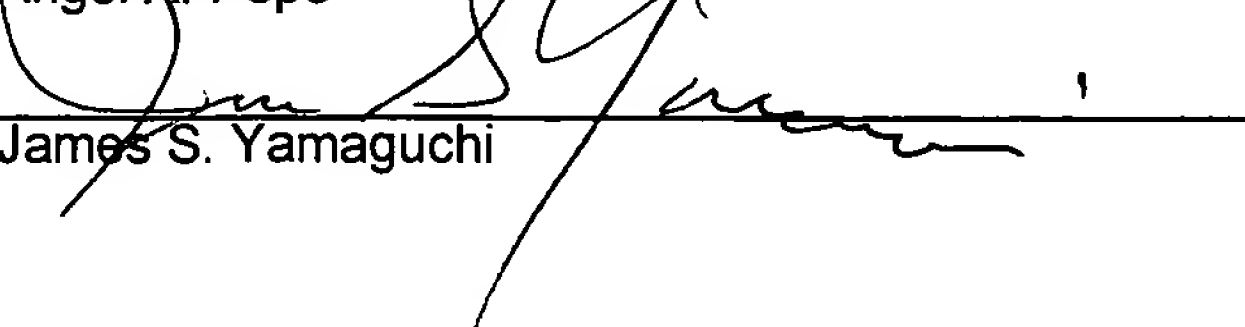
executed this

28<sup>th</sup> day of August, 2001

28<sup>th</sup> day of August, 2001

Signature of Inventor(s)

  
 \_\_\_\_\_  
 Angel A. Pepe

  
 \_\_\_\_\_  
 James S. Yamaguchi